



Alternate Assembly & Test Supplier for Trion® Devices

Dear Efinix Customer,

Efinix Inc. is providing this notification of changes to announce the addition of STATS ChipPAC Jiangyin Semiconductor Co., Ltd. (JSCC) as second outsourced assembly and test supplier (OSAT) for Trion T13F256 and T20F256 devices.

Change Description:

There is **slight change on the overall thickness** of the T13F256 and T20F256 devices that manufactured at JSCC but it is still within Efinix specification.

	Current OSAT	JSCC
Package Length and Width (mm)	13 x 13, +/- 0.05	13 x 13, +/- 0.05
Package Thickness (mm)	1.04 (nom), 1.14 (max)	1.03 (nom), 1.13 (max)

The package material set, and manufacturing processes are compatible with the T13F256 and T20F256 devices that Efinix currently supplies from other qualified OSAT.

Affected devices will be identified by alphabet “D” in the 1st digit of the date code marked on top of the devices (Figure 1).

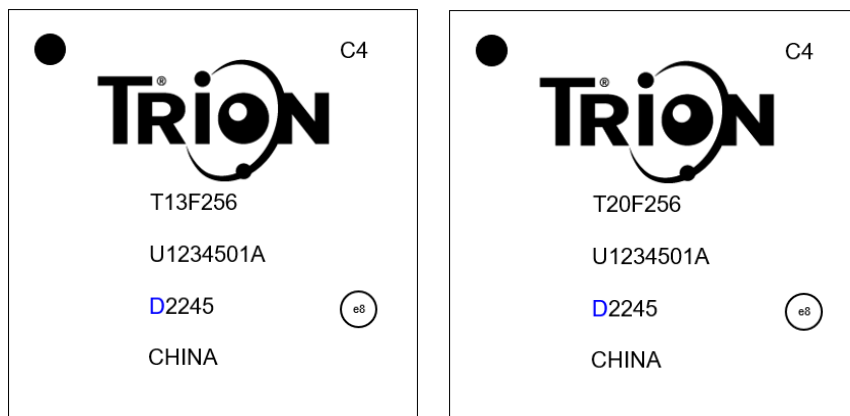


Figure 1 – Identifier for Device Manufactured at JSCC



Affected Products:

This change affects T13F256 and T20F256 devices from the Trion® product family.

T13F256C4	T20F256C4
T13F256C3	T20F256C3
T13F256I4	T20F256I4

Affected Manufacturing Facilities:

STATS ChipPAC Jiangyin Semiconductor Co., Ltd. (JSCC)

Reason for Change:

The reason for this change is to expand additional manufacturing capacity for Trion devices.

Date of Implementation:

Device assembled at JSCC will start shipping in Q3 '22 and can be identified with “D” prefix on the date code.

Samples for customer evaluation will be available by early August 2022. Order for customer samples can be placed now.

Upon receipt of PCN: If a written request for additional information or rejection is not provided to Efinix Inc. prior to 19-June-2022 the PCN will be considered accepted.

Supporting Data:

Qualification report will be available by mid of November 2022.

Contact:

For more information, please contact Sales & Marketing or Quality Assurance Engineering in your region.